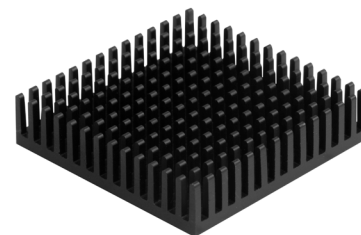




**MODEL:** HSB26-343408 | **DESCRIPTION:** HEAT SINK

**FEATURES**

- BGA design
- top mount
- aluminum alloy



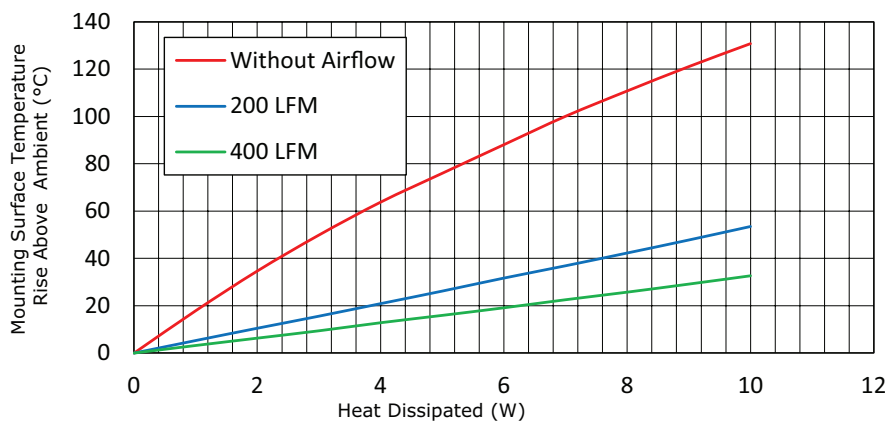
**MODEL**

HSB26-343408	thermal resistance <sup>1</sup>			power dissipation <sup>1</sup> @ 75°C ΔT, nat conv [W]
	@ 75°C ΔT, nat conv [°C/W]	@ 1 W, nat conv [°C/W]	@ 1 W, 200 LFM [°C/W]	
	15.19	17.9	5.3	4.94

Note: 1. See performance curves for full thermal resistance details.

**PERFORMANCE CURVES**

Power [W]	Heatsink Temperature Rise Above Ambient (ΔT = T <sub>hs</sub> - T <sub>a</sub> ) [°C]		
	Natural Conv.	200 LFM	400 LFM
0	0	0	0
1	17.9	5.3	3.2
2	34.7	10.5	6.3
3	49.9	15.6	9.4
4	63.8	20.9	12.8
5	76.0	26.2	15.9
6	88.1	31.7	19.1
7	100.1	36.9	22.5
8	110.8	42.3	25.7
9	121.1	47.8	29.1
10	130.8	53.5	32.6



T<sub>hs</sub>: "hot spot" temperature measured on the heatsink  
T<sub>a</sub>: ambient temperature

## MECHANICAL DRAWING

units: mm  
tolerance: ±0.5 mm

MATERIAL	AL 6063-T5
FINISH	black anodized
WEIGHT	15.6 g

